



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PLCC4 SMD with IC
- ▶ 3535IC 1.47t Series
- ▶ Red/Green/Blue

NOM45S36IC



Release Date: 15 September 2024 Version: A1.2



3535 IC-Integrated

RoHS
Compliant



FEATURES:

- **Package:** PLCC4 EIA STD Package with Integrated IC
- **Forward Current:** 12mA
- **Forward Voltage (typ.):** +3.8~+5.5V
- **Luminous Intensity (typ.):** 1500mcd mixed white
- **Colour:** Red/Green/Blue
- **Wavelength:** 622/525/467nm
- **Viewing angle:** 120°
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+105°C
- **IC Feature:**

The RGB and driver chip are integrated in a package to form a complete control of the pixel point with constant current. One Pixel contains R, G, and B colour each can achieve 256 level brightness greyscales, which form 16,777,216 combination colours. Internal clock frequency operates at 800kHz. Serial data transmission signal by single wire.

- **Soldering methods:** Reflow soldering
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with max.1300pcs/reel, ø180mm (7")

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- Decoration Lighting
- Full Colour LED Strip
- Gaming Device

CHARACTERISTICS:

 Absolute Maximum Characteristics ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I_F	12	mA
IC Power Supply Voltage	V_{DD}	+3.8~+5.5	V
IC Input Voltage	V_I	-0.4~ $V_{DD}+0.4$	V
Operating Temperature	T_{OPR}	-40~+85	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40~+105	$^\circ\text{C}$

 Electrical & Optical Characteristics ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Values			Unit	Test Condition	
		Min.	Typ.	Max.			
Luminous Intensity	R	I_v	---	380	---	mcd	$I_F=12\text{mA}$
	G		---	950	---		
	B		---	210	---		
	W		1000	1500	2100		
Dominant Wavelength	R	λ_D	615	---	630	nm	$I_F=12\text{mA}$
	G		520	---	530		
	B		460	---	475		
Colour Coordinate	X	---	---	0.2600	---	---	$I_F=12\text{mA}$
	Y		---	0.2600	---		
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	$I_F=12\text{mA}$	

Electrical & Optical Characteristics (Ta=25°C)

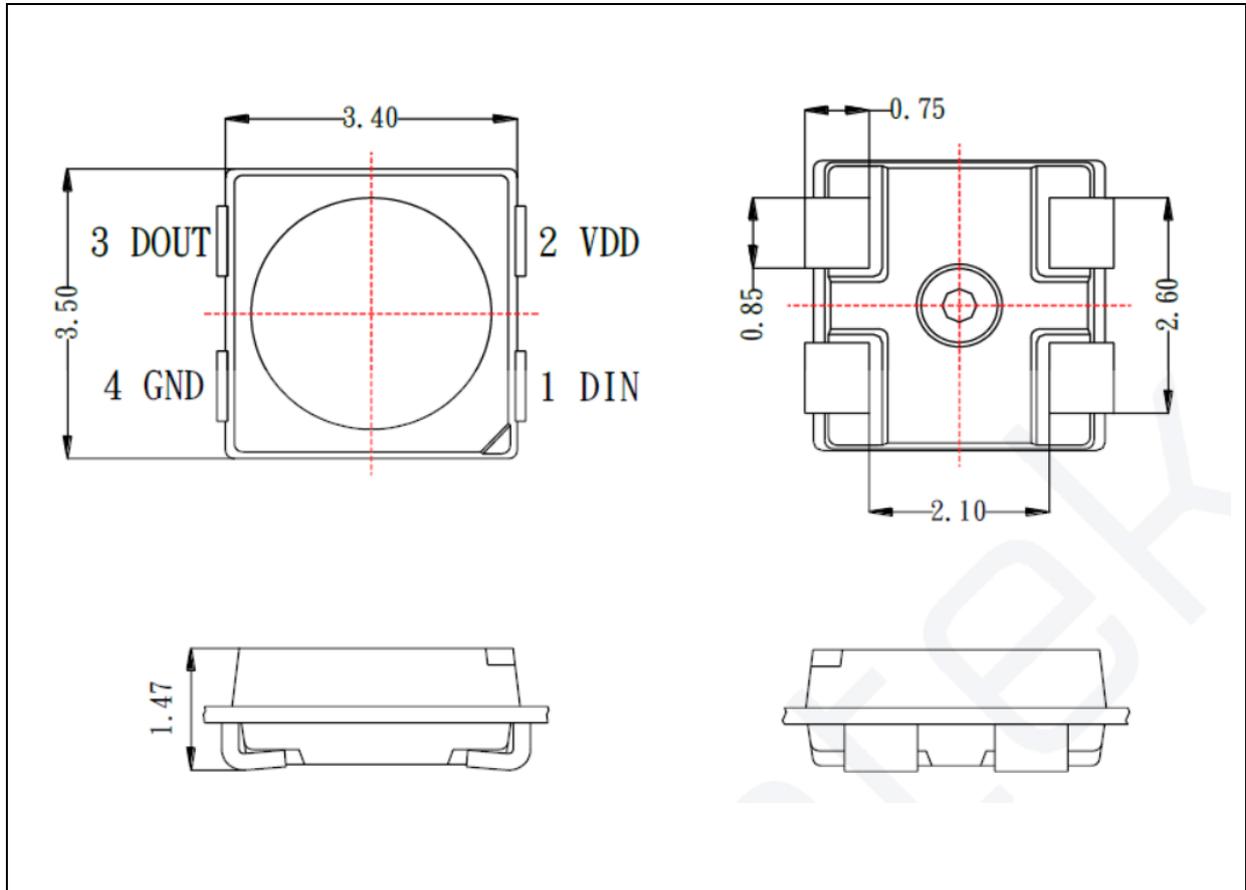
Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Static Current	I _{DD}	---	0.5	---	mA	V _{DD} =4.5V I _{OUT} =OFF
Input Voltage Level	V _{IH}	0.7 V _{DD}	---	---	V	D _{IN} , SET
	V _{IL}	---	---	0.3 V _{DD}	V	D _{IN} , SET

Switching Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Rate of Data Signal	F _{DIN}	---	0.8	---	MHz	---
Transfer Time	T _{PLH}	---	---	80	ns	D _{IN} -> D _{OUT}
	T _{PHL}	---	---	80	ns	
Conversion Time of I _{OUT} R/B	T _r	---	---	50	ns	I _{OUT} R/B=12mA RL=200Ω CL=30pF
	T _f	---	---	100	ns	
Conversion Time of I _{OUT} G	T _r	---	---	30	ns	I _{OUT} G=12mA RL=200Ω CL=30pF
	T _f	---	---	150	ns	

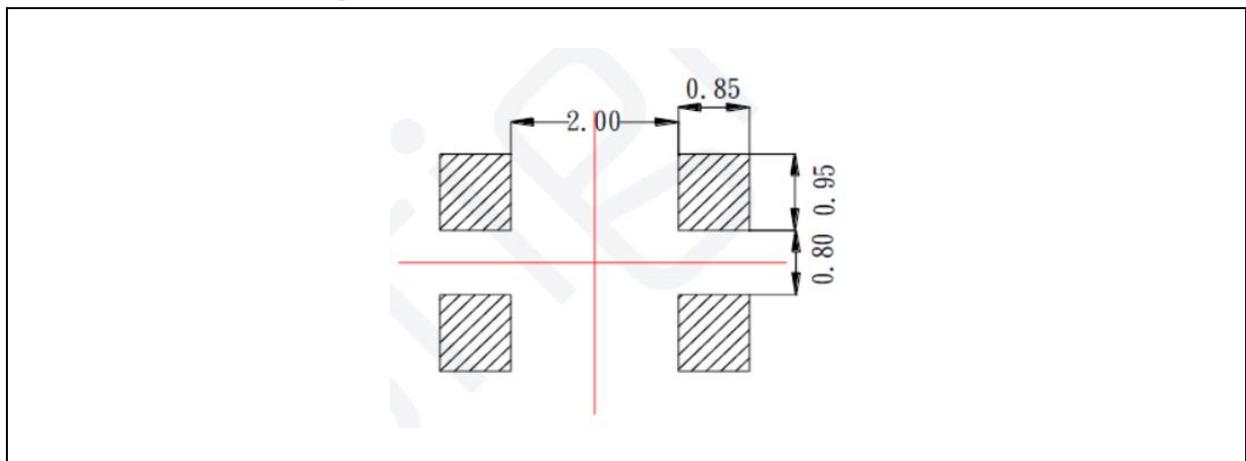
OUTLINE DIMENSION:

Package Dimension:



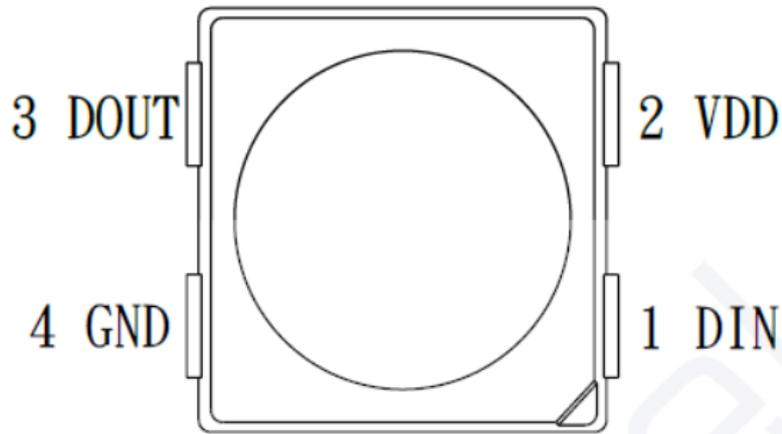
1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

PIN CONFIGURATION:



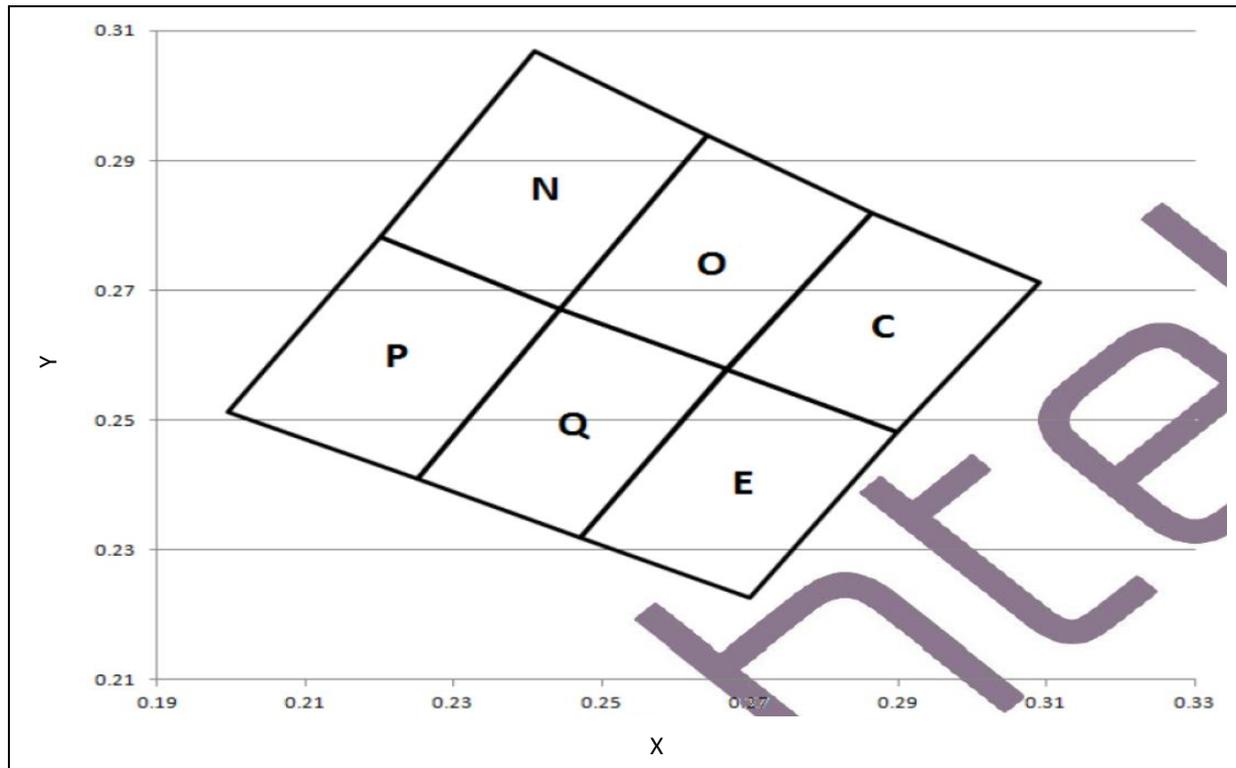
No.	Symbol	Function Description
1	DIN	Control data signal input
2	VDD	Power Supply LED
3	DOUT	Control data signal output
4	GND	Ground

BINNING GROUPS:

Luminous Intensity Classifications (White) ($I_F = 12\text{mA}$):

Code	Min.	Max.	Unit
15	1000	1300	mcd
16	1300	1700	
17	1700	2200	

CIE Chromaticity Diagram:

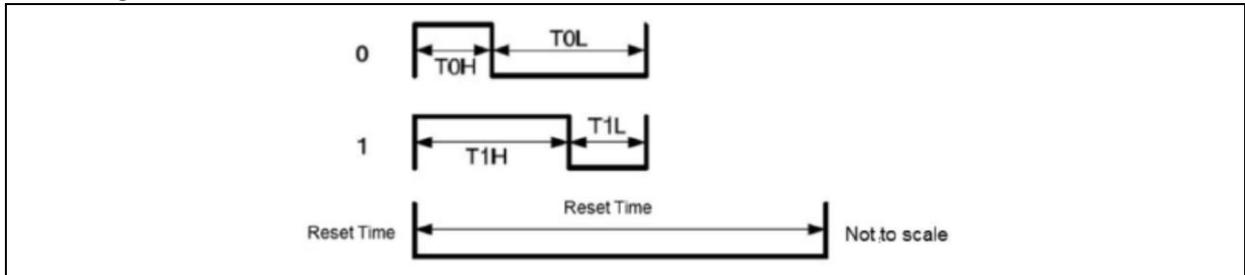


Chromaticity Coordinates Classifications ($I_F = 12\text{mA}$):

	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
E	0.2667	0.2578	0.2899	0.2482	0.2700	0.2227	0.2470	0.2320
P	0.2200	0.2783	0.1996	0.2513	0.2250	0.2410	0.2444	0.2672
Q	0.2444	0.2672	0.2250	0.2410	0.2471	0.2320	0.2669	0.2579
C	0.2865	0.2819	0.3091	0.2712	0.2899	0.2482	0.2667	0.2578
O	0.2444	0.2672	0.2643	0.2940	0.2863	0.2820	0.2669	0.2579
N	0.2200	0.2783	0.2408	0.3068	0.2643	0.2940	0.2444	0.2672

DATA TRANSFER TIME ($T_H+T_L=1.2\mu s\pm 600ns$):

1. Timing Wave Form



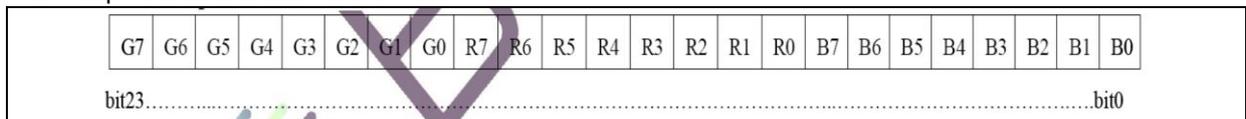
2. High Speed Mode

Item	Description	Typical	Allowance
T_{0H}	0 code, high voltage time	300ns	$\pm 150ns$
T_{1H}	1 code, high voltage time	900ns	$\pm 150ns$
T_{0L}	0 code, low voltage time	900ns	$\pm 150ns$
T_{1L}	1 code, low voltage time	300ns	$\pm 150ns$
RES	Reset Time	$>200\mu s$	---

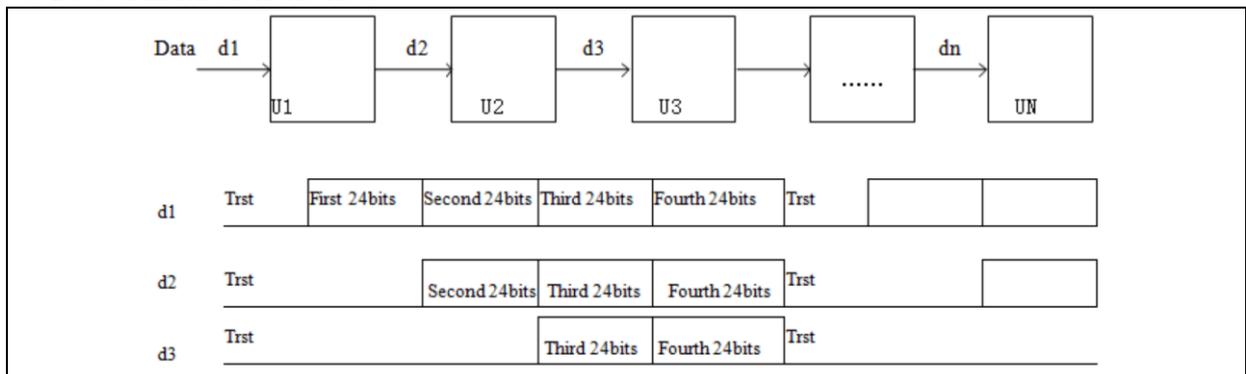
Note:

1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
2. $\Theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial intensity.
3. The dominant wavelength, λ_d is derived from CIE chromaticity diagram and represents the single wavelength which defines the colour of the device. Peak emission wavelength tolerance is $\pm 1nm$.

3. Composition of 24 Bits Data

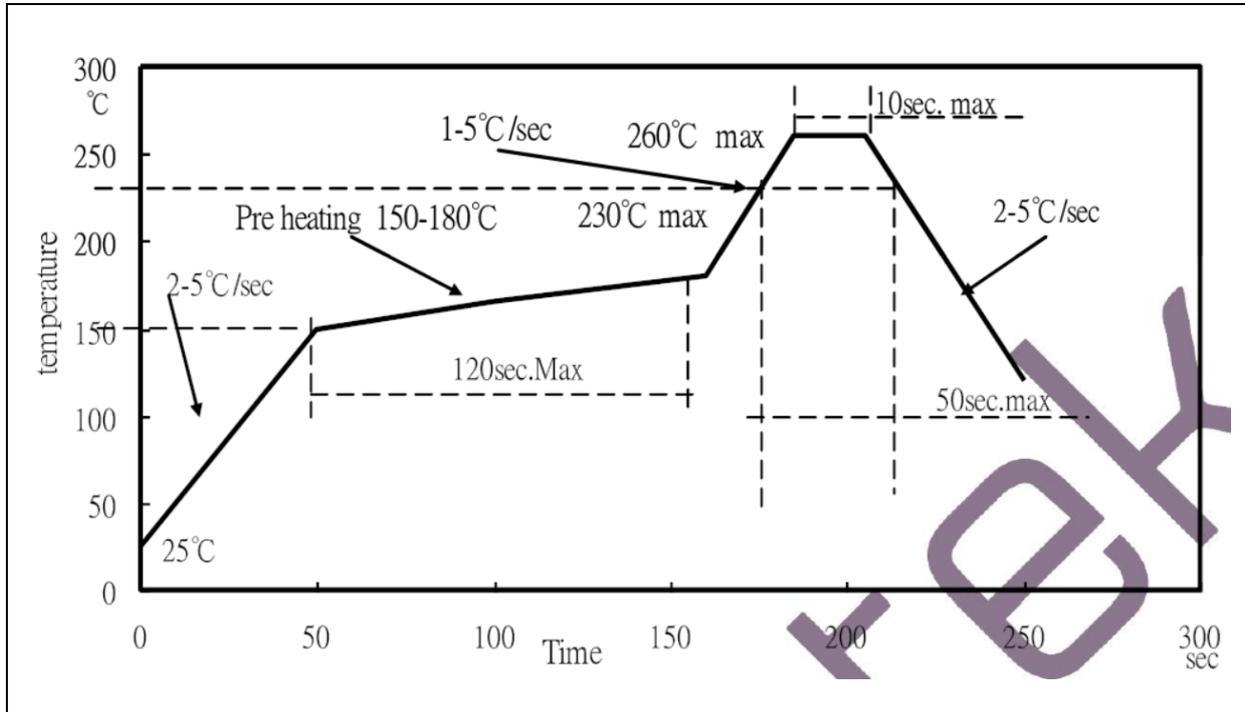


3. Data Transmission Method



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:

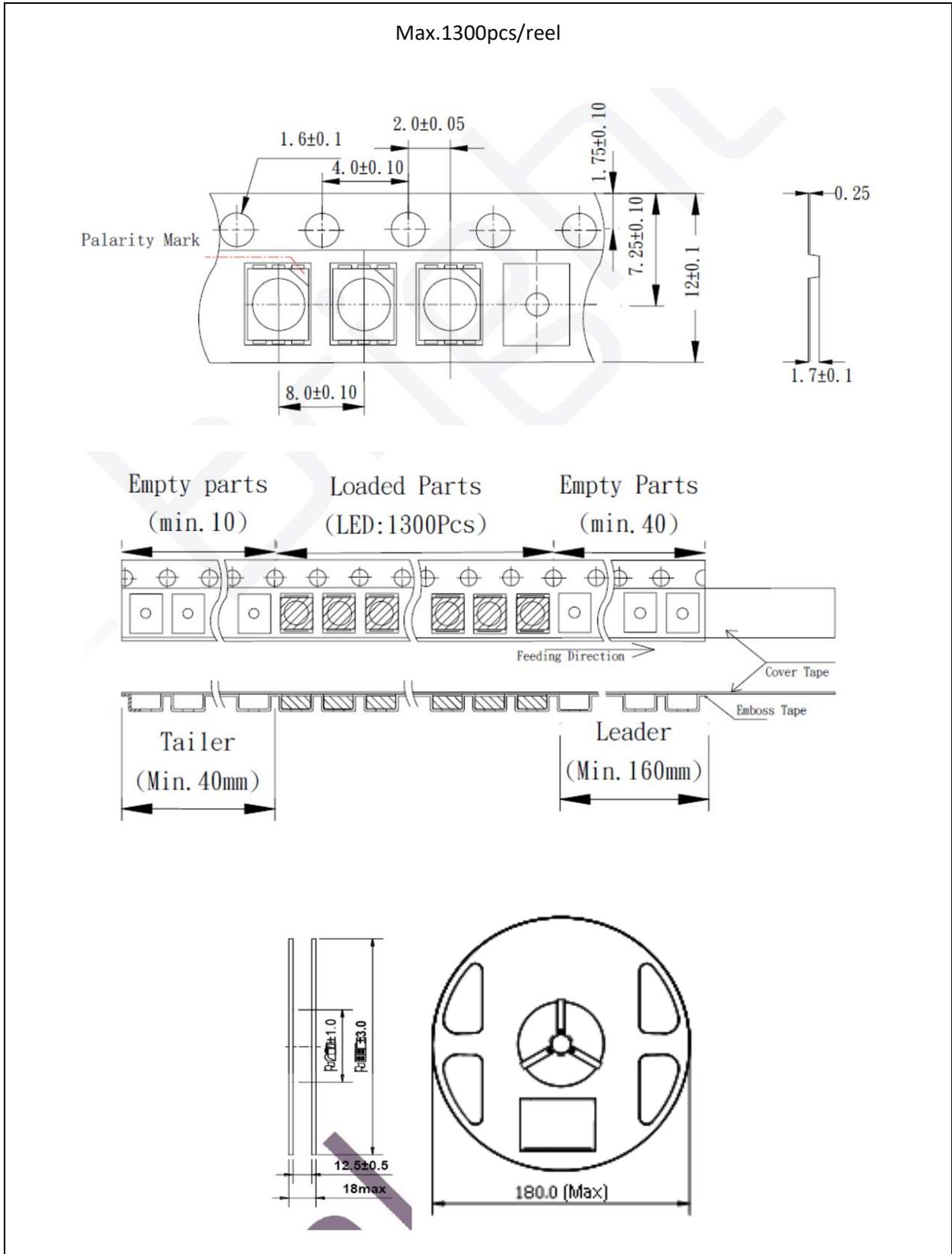


Note:

1. We recommend the reflow temperature 245°C ($\pm 5^\circ\text{C}$). The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burn-out will happen.

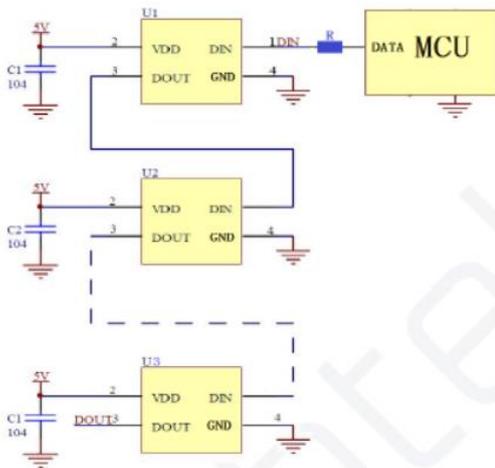
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 6hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	15/09/2024	Datasheet set-up.